

ON Semiconductor			10/15/2019	
Base Part		FSV20120V	HF	
Orderable Part		FSV20120V	Total weight (mg)	91.999991
Homogenous Material	Weight (mg)	Substance in Mat.	CAS #	% Avg. Weight
Clip	4.942	Iron (Fe)	7439-89-6	3
		Copper (Cu)	7440-50-8	97
Die	9.594	Silicon (Si)	7440-21-3	100
Die Attach Solder	4.165	Silver (Ag)	7440-22-4	2.5
		Lead (Pb)	7439-92-1	92.5
		Tin (Sn)	7440-31-5	5
Lead Frame	30.081	Iron (Fe)	7439-89-6	0.14959609
		Copper (Cu)	7440-50-8	99.80053855
		Phosphorus (P)	7723-14-0	0.04986536
Mold Compound-Black	43.216991	Ortho Cresol Novolac Resin	29690-82-2	10.00000208
		Carbon Black (C)	1333-86-4	0.30000006
		Fused Silica (SiO2)	60676-86-0	79.69999577
		Phenolic Resin (Novolac)	9003-35-4	10.00000208
Plating	0.001	Tin (Sn)	7440-31-5	100
<p>Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the most accurate information, we cannot guarantee to its accuracy since the data has been compiled based on the ranges provided, and some information provided by the subcontractors and raw material suppliers may have been withheld to protect their business proprietary information. Thus this information is provided only as estimates, and do not include trace levels fo dopants and metal materials contained within silicon devices in the finished products. There is no intentional use of Mercury, Hexavalent Chromium, Cadmium, PBB or PBDE (5 of the 6 RoHS banned substances) in this or any of our other products. For further explanation on material composition calculations, please view our Product Chemical Content Brochure at:</p> <p>http://www.onsemi.com/pub/Collateral/BRD8022-D.PDF</p>				